



Material Content Data Sheet



Sales Product Name				SPD08P06P G		Issued		1. August 2018	
MA#				MA001725272					
Package				PG-TO252-3-311		Weight*		312.94 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.145	0.37	0.37	3658	3658	
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		137		
	non noble metal	iron	7439-89-6	0.143	0.05		458		
	non noble metal	copper	7440-50-8	143.098	45.72	45.78	457269	457864	
	non noble metal	aluminium	7429-90-5	0.502	0.16	0.16	1605	1605	
wire	inorganic material	antimonytrioxide	1309-64-4	2.012	0.64		6428		
encapsulation	plastics	brominated resin	-	2.155	0.69		6888		
	organic material	carbon black	1333-86-4	2.299	0.73		7347		
	plastics	epoxy resin	-	19.399	6.20		61989		
	inorganic material	silicondioxide	60676-86-0	117.830	37.65	45.91	376524	459176	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.20	1.20	11951	11951	
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	276	277	
solder	non noble metal	tin	7440-31-5	0.026	0.01		82		
	noble metal	silver	7440-22-4	0.032	0.01		103		
	non noble metal	lead	7439-92-1	1.228	0.39	0.41	3924	4109	
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	iron	7439-89-6	0.019	0.01		61		
	non noble metal	copper	7440-50-8	19.177	6.13	6.14	61281	61360	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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